Dual Complementary General Purpose Transistor

The NST3946DP6T5G device is a spin-off of our popular SOT-23/SOT-323/SOT-563 three-leaded device. It is designed for general purpose amplifier applications and is housed in the SOT-963 six-leaded surface mount package. By putting two discrete devices in one package, this device is ideal for low-power surface mount applications where board space is at a premium.

Features

- h_{FE}, 100-300
- Low $V_{CE(sat)}$, $\leq 0.4 \text{ V}$
- Reduces Board Space and Component Count
- NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free and are RoHS Compliant

MAXIMUM RATINGS

Rating		Symbol	Value	Unit
Collector - Emitter Voltage		V_{CEO}	40	Vdc
Collector - Base Voltage		V_{CBO}	60	Vdc
Emitter - Base Voltage		V _{EBO}	6.0	Vdc
Collector Current - Continuous		I _C	200	mAdc
Electrostatic Discharge	HBM MM	ESD Class	2 B	

THERMAL CHARACTERISTICS

Characteristic (Single Heated)	Symbol	Max	Unit
Total Device Dissipation T _A = 25°C Derate above 25°C (Note 1)	P _D	240 1.9	mW mW/°C
Thermal Resistance, Junction-to-Ambient (Note 1)	$R_{\theta JA}$	520	°C/W
Total Device Dissipation T _A = 25°C Derate above 25°C (Note 2)	P _D	280 2.2	mW mW/°C
Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{\theta JA}$	446	°C/W
Characteristic (Dual Heated) (Note 3)	Symbol	Max	Unit
Total Device Dissipation T _A = 25°C Derate above 25°C (Note 1)	P _D	350 2.8	mW mW/°C
Thermal Resistance, Junction-to-Ambient (Note 1)	$R_{\theta JA}$	357	°C/W
Total Device Dissipation T _A = 25°C Derate above 25°C (Note 2)	P _D	420 3.4	mW mW/°C
Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{\theta JA}$	297	°C/W
Junction and Storage Temperature Range	T _J , T _{stg}	-55 to +150	°C

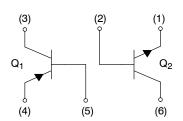
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. FR-4 @ 100 mm², 1 oz. copper traces, still air.
- 2. FR-4 @ 500 mm², 1 oz. copper traces, still air.
- 3. Dual heated values assume total power is sum of two equally powered channels



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NST3946DP6T5G*

*Q1 PNP Q2 NPN



SOT-963 CASE 527AD

MARKING DIAGRAM



= Device Code

(180° Clockwise Rotation)

M = Date Code

ORDERING INFORMATION

Device	Package	Shipping [†]
NST3946DP6T5G	SOT-963 (Pb-Free)	8000/Tape & Reel
NSVT3946DP6T5G	SOT-963 (Pb-Free)	8000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic		Symbol	Min	Max	Unit
OFF CHARACTERISTICS					
Collector – Emitter Breakdown Voltage (Note 4) ($I_C = 1.0 \text{ mAdc}$, $I_B = 0$) ($I_C = -1.0 \text{ mAdc}$, $I_B = 0$)	(NPN) (PNP)	V _{(BR)CEO}	40 -40	- -	Vdc
Collector – Base Breakdown Voltage ($I_C = 10 \mu Adc, I_E = 0$) ($I_C = -10 \mu Adc, I_E = 0$)	(NPN) (PNP)	V _(BR) CBO	60 -40		Vdc
Emitter – Base Breakdown Voltage ($I_E = 10 \mu Adc, I_C = 0$) ($I_E = -10 \mu Adc, I_C = 0$)	(NPN) (PNP)	V _{(BR)EBO}	6.0 -5.0	- -	Vdc
Collector Cutoff Current (V_{CE} = 30 Vdc, V_{EB} = 3.0 Vdc) (V_{CE} = -30 Vdc, V_{EB} = -3.0 Vdc)	(NPN) (PNP)	I _{CEX}	- -	50 –50	nAdc
ON CHARACTERISTICS (Note 4)					
DC Current Gain $ \begin{array}{l} (I_{C}=0.1 \text{ mAdc, } V_{CE}=1.0 \text{ Vdc)} \\ (I_{C}=1.0 \text{ mAdc, } V_{CE}=1.0 \text{ Vdc)} \\ (I_{C}=10 \text{ mAdc, } V_{CE}=1.0 \text{ Vdc)} \\ (I_{C}=50 \text{ mAdc, } V_{CE}=1.0 \text{ Vdc)} \\ (I_{C}=100 \text{ mAdc, } V_{CE}=1.0 \text{ Vdc)} \\ \end{array} $	(NPN)	h _{FE}	40 70 100 60 30	- 300 - -	-
$ \begin{array}{l} (I_C = -0.1 \text{ mAdc, } V_{CE} = -1.0 \text{ Vdc}) \\ (I_C = -1.0 \text{ mAdc, } V_{CE} = -1.0 \text{ Vdc}) \\ (I_C = -10 \text{ mAdc, } V_{CE} = -1.0 \text{ Vdc}) \\ (I_C = -50 \text{ mAdc, } V_{CE} = -1.0 \text{ Vdc}) \\ (I_C = -100 \text{ mAdc, } V_{CE} = -1.0 \text{ Vdc}) \end{array} $	(PNP)		60 80 100 60 30	- 300 - -	
Collector – Emitter Saturation Voltage ($I_C = 10 \text{ mAdc}$, $I_B = 1.0 \text{ mAdc}$) ($I_C = 50 \text{ mAdc}$, $I_B = 5.0 \text{ mAdc}$)	(NPN)	V _{CE(sat)}	- -	0.2 0.3	Vdc
$(I_C = -10 \text{ mAdc}, I_B = -1.0 \text{ mAdc})$ $(I_C = -50 \text{ mAdc}, I_B = -5.0 \text{ mAdc})$	(PNP)		- -	-0.25 -0.4	
Base – Emitter Saturation Voltage (I_C = 10 mAdc, I_B = 1.0 mAdc) (I_C = 50 mAdc, I_B = 5.0 mAdc)	(NPN)	V _{BE(sat)}	0.65 -	0.85 0.95	Vdc
$(I_C = -10 \text{ mAdc}, I_B = -1.0 \text{ mAdc})$ $(I_C = -50 \text{ mAdc}, I_B = -5.0 \text{ mAdc})$	(PNP)		-0.65 -	-0.85 -0.95	

^{4.} Pulse Test: Pulse Width \leq 300 μ s; Duty Cycle \leq 2.0%.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted) (Continued)

Characteristic			Symbol	Min	Max	Unit
SMALL-SIGNAL (CHARACTERISTICS					
(0)		(NPN) (PNP)	f _T	200 250	- -	MHz
Output Capacitance (V _{CB} = 5.0 Vdc, I _E (V _{CB} = -5.0 Vdc, I	= 0, f = 1.0 MHz) E = 0, f = 1.0 MHz)	(NPN) (PNP)	C _{obo}	- -	4.0 4.5	pF
Input Capacitance (V _{EB} = 0.5 Vdc, I _C (V _{EB} = -0.5 Vdc, I	= 0, f = 1.0 MHz) C = 0, f = 1.0 MHz)	(NPN) (PNP)	C _{ibo}		8.0 10.0	pF
Noise Figure $ \begin{array}{l} \text{($V_{CE}=5.0$ Vdc, $I_{C}=100$ μAdc, $R_{S}=1.0$ k Ω, $f=1.0$ kHz)} \\ \text{($V_{CE}=-5.0$ Vdc, $I_{C}=-100$ μAdc, $R_{S}=1.0$ k Ω, $f=1.0$ kHz)} \end{array} $		(NPN) (PNP)	NF	-	5.0 4.0	dB
SWITCHING CHAI	RACTERISTICS					
Delay Time	$(V_{CC} = 3.0 \text{ Vdc}, V_{BE} = -0.5 \text{ Vdc})$ $(V_{CC} = -3.0 \text{ Vdc}, V_{BE} = 0.5 \text{ Vdc})$	(NPN) (PNP)	t _d		35 35	
Rise Time	$(I_C = 10 \text{ mAdc}, I_{B1} = 1.0 \text{ mAdc})$ $(I_C = -10 \text{ mAdc}, I_{B1} = -1.0 \text{ mAdc})$	(NPN) (PNP)	t _r	- -	35 35	ns
Storage Time	$(V_{CC} = 3.0 \text{ Vdc}, I_C = 10 \text{ mAdc})$ $(V_{CC} = -3.0 \text{ Vdc}, I_C = -10 \text{ mAdc})$	(NPN) (PNP)	t _s	- -	275 250	
Fall Time	$(I_{B1} = I_{B2} = 1.0 \text{ mAdc})$ $(I_{B1} = I_{B2} = -1.0 \text{ mAdc})$	(NPN) (PNP)	t _f		50 50	ns

NPN TRANSISTOR

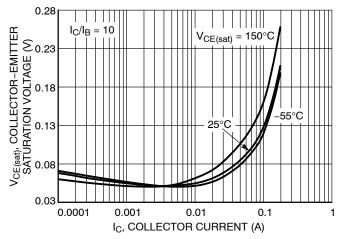


Figure 1. Collector Emitter Saturation Voltage vs. Collector Current

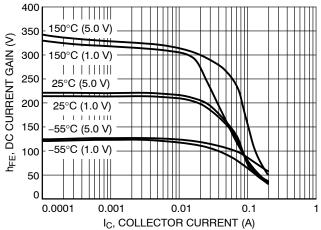


Figure 2. DC Current Gain vs. Collector Current

NPN TRANSISTOR

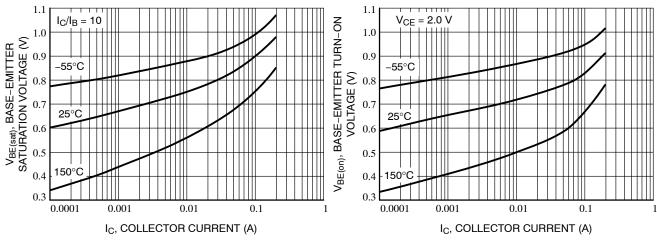


Figure 3. Base Emitter Saturation Voltage vs. Collector Current

Figure 4. Base Emitter Turn-On Voltage vs. Collector Current

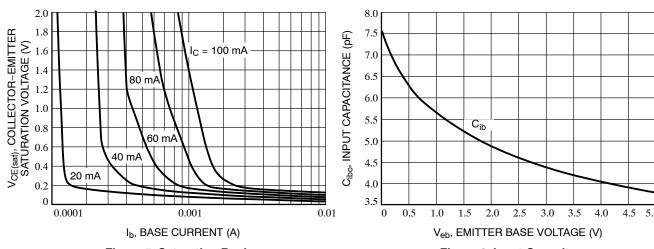


Figure 5. Saturation Region

Figure 6. Input Capacitance

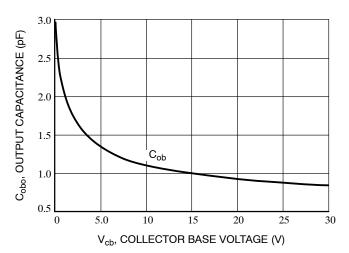


Figure 7. Output Capacitance

PNP TRANSISTOR

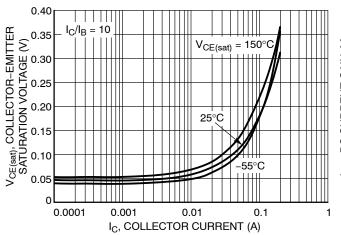


Figure 8. Collector Emitter Saturation Voltage vs. Collector Current

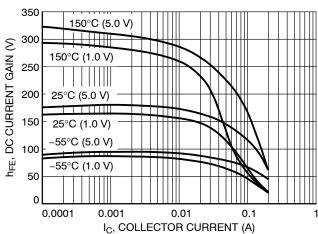


Figure 9. DC Current Gain vs. Collector Current

PNP TRANSISTOR

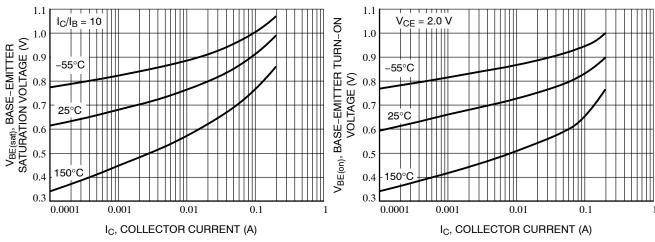


Figure 10. Base Emitter Saturation Voltage vs.
Collector Current

Figure 11. Base Emitter Turn-On Voltage vs.
Collector Current

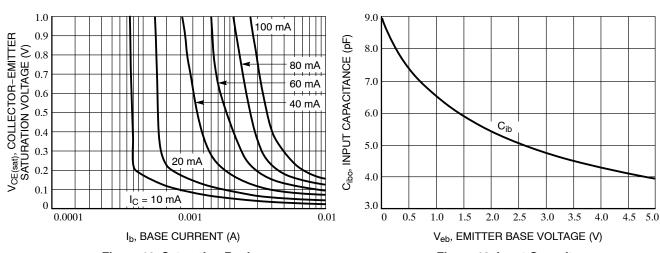


Figure 12. Saturation Region

Figure 13. Input Capacitance

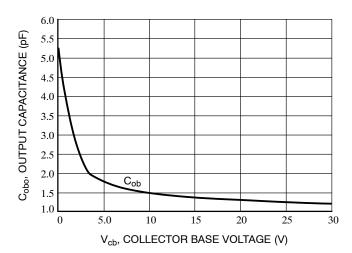


Figure 14. Output Capacitance

MECHANICAL CASE OUTLINE

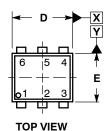


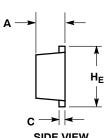


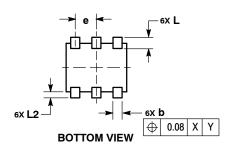
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DATE 09 FEB 2010

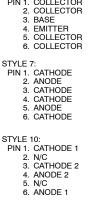




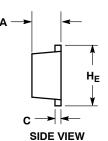




STYLE 1: PIN 1. EMITTER 1 2. BASE 1 3. COLLECTOR 2 4. EMITTER 2 5. BASE 2 6. COLLECTOR 1
STYLE 4: PIN 1. COLLECTOR 2. COLLECTOR 3. BASE 4. EMITTER 5. COLLECTOR 6. COLLECTOR
STYLE 7: PIN 1. CATHODE 2. ANODE 3. CATHODE 4. CATHODE 5. ANODE 6. CATHODE



STYLE 2: PIN 1. EMITTER 1 2. EMITTER2 3. BASE 2 4. COLLECTOR 2 5. BASE 1 6. COLLECTOR 1	STYLE 3: PIN 1. CATHODE 1 2. CATHODE 1 3. ANODE/ANODE 2 4. CATHODE 2 5. CATHODE 2 6. ANODE/ANODE 1
STYLE 5:	STYLE 6:
PIN 1. CATHODE 2. CATHODE	PIN 1. CATHODE 2. ANODE
3. ANODE	3. CATHODE
4. ANODE	4. CATHODE
5. CATHODE 6. CATHODE	5. CATHODE 6. CATHODE
STYLE 8:	STYLE 9:
PIN 1. DRAIN	PIN 1. SOURCE 1
2. DRAIN 3. GATE	2. GATE 1 3. DRAIN 2
4. SOURCE	4. SOURCE 2
5. DRAIN	5. GATE 2
6. DRAIN	6. DRAIN 1



NOTES:

- DIMENSIONING AND TOLERANCING PER ASME
- DIMENSIONING AND TOLEHANCING PER ASM Y14.5M, 1994.
 CONTROLLING DIMENSION: MILLIMETERS
 MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL
- 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	MILLIMETERS			
DIM	MIN	NOM	MAX	
Α	0.34	0.37	0.40	
b	0.10	0.15	0.20	
С	0.07	0.12	0.17	
D	0.95	1.00	1.05	
E	0.75	0.80	0.85	
е	0.35 BSC			
HE	0.95	1.00	1.05	
L	0.19 REF			
L2	0.05	0.10	0.15	

GENERIC MARKING DIAGRAM*

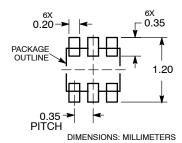


= Specific Device Code = Month Code Μ

*This information is generic. Please refer to device data sheet for actual part marking.

Pb-Free indicator, "G" or microdot " ■", may or may not be present.

RECOMMENDED MOUNTING FOOTPRINT



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DESCRIPTION:	SOT-963, 1X1, 0.35P		PAGE 1 OF 1	

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